

U.S. PATENT & TRADEMARK OFFICE  
FEB 14 2005  
IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Lee et al.

Attorney Docket No.:  
NOVLP033X1/NVLS-000498X1

Application No.: 10/649,351

Examiner: UNASSIGNED

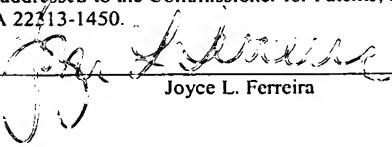
Filed: August 26, 2003

Group: UNASSIGNED

Title: METHOD FOR REDUCING TUNGSTEN  
FILM ROUGHNESS AND IMPROVING  
STEP COVERAGE

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the U.S. Postal Service with sufficient postage as first-class mail on February 9, 2005 in an envelope addressed to the Commissioner for Patents, P.O. Box 1450 Alexandria, VA 22313-1450.

Signed: 

Joyce L. Ferreira

INFORMATION DISCLOSURE STATEMENT WITH STATEMENT  
UNDER 37 CFR §§1.56 AND 1.97

Mail Stop Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

The references listed in the attached PTO Form 1449 copies of which are enclosed, may be material to the examination of the above-identified patent application. These references were cited in a corresponding PCT application. A copy of the PCT Search Report which was dated October 15, 2004, and was mailed on January 19, 2005, is enclosed herewith as well. These references are submitted in compliance with the applicant's duty of disclosure pursuant to 37 CFR §§1.56 and 1.97. Accordingly, the Examiner is requested to make these citations official record in this application.

This Information Disclosure Statement is not to be construed as a representation that additional information (material to the examination of this application) does not exist or that the enclosed reference(s) constitute prior art.

**Statement under 37 CFR § 1.97(e)**

The undersigned hereby states that the references enclosed herewith were cited in a communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of the information disclosure statement. (37 CFR 1.97(e)(1))

**Statement Under 37 CFR §1.704(d)**

Each item of information contained in the Information Disclosure Statement was cited in a communication from a foreign patent office in a counterpart application; this communication was not received by any individual designated in §1.56(c) more than thirty days prior to the filing of the Information Disclosure Statement.

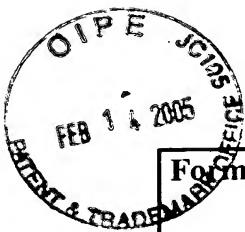
Accordingly, it is respectfully submitted that no fee is due in conjunction with the filing of this IDS. However, should the Commissioner determine that additional fees are required for filing the present Information Disclosure Statement, the Commissioner is hereby authorized to charge any such fees to our deposit account number 500388 (Order No. NOVLP033X1).

Respectfully submitted,  
BEYER WEAVER & THOMAS, LLP



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<b>Form 1449 (Modified)</b> <b>Information Disclosure Statement By Applicant</b> (Use Several Sheets if Necessary)		Atty Docket No. NOVLP033X1/NVLS-000498X1 Applicant: Lee et al. Filing Date August 26, 2003	Application No.: 10/649,351
			Group 1762

#### U.S. Patent Documents

Examiner Initial	No.	Patent No.	Date	Patentee	Class	Sub-class	Filing Date
	A1	5,661,080	08/26/97	Hwang et al.			12/10/93
	A2	2003/127043	07/10/03	Lu et al.			07/12/02
	A3	2003/059980	03/27/03	Chen et al.			09/25/01
	A4	2002/090796	07/11/02	Desai et al.			10/16/01

#### Foreign Patent or Published Foreign Patent Application

Examiner Initial	No.	Document No.	Publication Date	Country or Patent Office	Class	Sub-class	Translation	
							Yes	No
	B1							

#### Other Documents

Examiner Initial	No.	Author, Title, Date, Place (e.g. Journal) of Publication
	C1	Lee et al., PCT Search Report, Completed October 15, 2004, PCT/US2004/006940, Int'l filing date May 3, 2004
	C2	Lee et al., Written Opinion, Completed October 15, 2004, PCT/US2004/006940, Int'l filing date May 3, 2004
	C3	
	C4	
Examiner		Date Considered

Examiner: Initial citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.